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Electronic Version v1.1

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Title of
Invention

METHOD FOR FORMING ROBUST SOLDER INTERCONNECT STRUCTURES BY REDUCING EFFECTS OF SEED LAYER UNDERETCHING

Application Number:

Date:

First Named Applicant:

Kamalesh K. Srivastava

Confirmation Number:

Attorney Docket Number:

FIS920030359US1

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Submitted By:	Elec. Sign.	Sign. Capacity
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Registered Number: 51,564	/	

Documents being submitted:	Files	
us foo aboot	FIS920030359US1-usfees.xml	
us-fee-sheet	us-fee-sheet.xsl	
	us-fee-sheet.dtd	
us-ids	FIS920030359US1-usidst.xml	
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application-body	FIS92030359US1-trans.xml	
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Comments

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